

ABSTRACT OF THE DISCLOSURE

5 A die used for molding an electronic component with resin includes a fixed, top die (1) and a movable, bottom die (2) and at least has a surface contacting a melted resin material that is electroplated (A) with nickel-tungsten alloy (NiW). This plating can provide releaseability of a resin-molded body (13) and the like superior to hard-chromium plating (HCr) to allow an ejector pin (14, 15) to efficiently eject and release the resin-molded body (13) from the die.

This Sheet Has Been Replaced

